RoBAT

For **double-sided** testing

For **single-sided** testing (double-sided boards can be flipped over to test second side)

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Machine Features Comparison Chart		RoBAT S1	RoBAT RCI	RoBAT VTR	R⊚BAT PDM-HS	R⊚BAT RTU	RoBAT CTR	RoBAT HTR	R <sub>O</sub> BAT Scara TDR-M	RoBAT Scara-PDM
TEST FUNCTIONS	Automatic Optical Inspection (AOI)	<b>*</b>	<b>/</b>						<b>/</b>	
	DC Electrical Test (capacitance)	<b>*</b>	<b>/</b>							
	DC Electrical Test (resistive)	<b>√</b> 2	<b>√</b> 2							
	TDR High Speed SI Test		<b>/</b>	<b>*</b>		<b>*</b>	<b>/</b>	<b>✓</b>	<b>/</b>	
	TDT High Speed SI Test		<b>/</b>	<b>~</b>						
	VNA High Speed SI Test		<b>√</b> 2	<b>/</b>						
	DMM Electrical Component Test	<b>*</b>	<b>/</b>							
	Mechanical Measurement Test	<b>/</b>	<b>✓</b>							
	Pin Depth Measurement	<b>/</b>	<b>*</b>		<b>/</b>					<b>/</b>
	High Voltage	<b>√</b> 1	<b>√</b> 1							
	Automatic Optical Hole Measurement				<b>*</b>					<b>/</b>
				<u> </u>		<u> </u>	1	<u> </u>		<u> </u>
FAULT COVERAGE	Mating Side Missing/Bent Pins	<b>/</b>	<b>/</b>							
	Other AOI Faults - Guide Pins etc.	<b>~</b>	•							
	Bent Under Compliant Pins (under connector)		<b>√</b> <sub>3</sub>	✓3	<b>*</b>		✓3	✓3	<b>√</b> <sub>3</sub>	<b>—</b>
	Missing Compliant Pins (under connector)		✓3	✓3	<b>*</b>		✓3	✓3	✓3	<b>—</b>
	Concertina Compliant Pins (under connector)		<b>√</b> <sub>3</sub>	<b>√</b> 3	<b>*</b>		<b>√</b> <sub>3</sub>	<b>√</b> <sub>3</sub>	<b>√</b> <sub>3</sub>	<b>—</b>
	Incorrect Back Drilling		<b>/</b>	<b>*</b>		<b>/</b>	<b>/</b>	<b>~</b>	<b>/</b>	<b>/</b>
	Skew Faults		<b>/</b>	<b>*</b>		<b>/</b>	<b>/</b>	<b>*</b>	<b>/</b>	
	Impedance Faults		<b>/</b>	<b>✓</b>		<b>*</b>	<b>/</b>	<b>✓</b>	<b>/</b>	
	Shorts	<b>~</b>	<b>*</b>	<b>*</b>		<b>✓</b>	<b>*</b>	<b>*</b>	<b>/</b>	
	Opens	<b>~</b>	<b>/</b>	<b>~</b>		<b>*</b>	<b>/</b>	<b>*</b>	<b>/</b>	
	Electrical Component Faults	<b>✓</b>	<b>/</b>							

- 1 Available as an option 2 Available with 4-head option
- **3** Using TDR/VNA measurement (depends on board architecture)